2.0x1.25mm SMD CHIP LED LAMP

APTK2012SYC

SUPER BRIGHT YELLOW

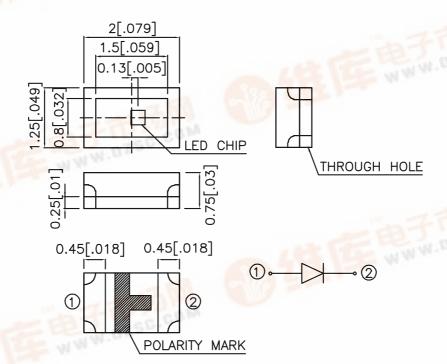
Features

- ●2.0mmx1.25mm SMT LED, 0.75mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACK LIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- ●PACKAGE: 2000PCS / REEL.

Description

The Super Bright Yellow devices is made with DH InGaAIP (on GaAs substrate) light emitting diode chip.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

SPEC NO: DSAD1120 REV NO: V.2 DATE: FEB/28/2005 PAGE: 1 OF 4

Selection Guide

Part No.	Dice	Dice Lens Type		icd) ImA	Viewing Angle
			Min.	Тур.	2 θ 1/2
APTK2012SYC	SUPER BRIGHT YELLOW (InGaAIP)	WATER CLEAR	50	120	100°

Note:

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	IF=20mA
λD	Dominant Wavelength	Super Bright Yellow	588		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	28		nm	IF=20mA
С	Capacitance	Super Bright Yellow	25		pF	VF=0V;f=1MHz
VF	Forward Voltage	Super Bright Yellow	2.0	2.5	V	IF=20mA
lr	Reverse Current	Super Bright Yellow		10	uA	VR = 5V

Absolute Maximum Ratings at TA=25°C

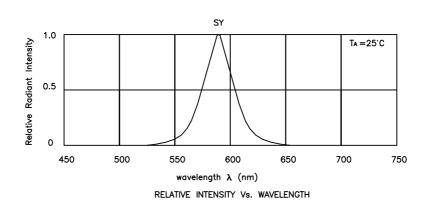
Parameter	Super Bright Yellow	Units
Power dissipation	125	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:

SPEC NO: DSAD1120 REV NO: V.2 DATE: FEB/28/2005 PAGE: 2 OF 4

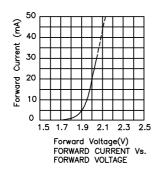
^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

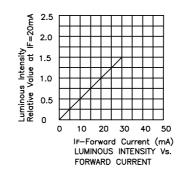
^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

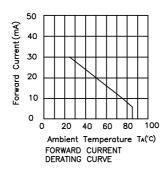


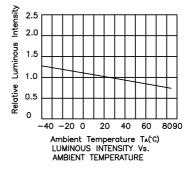
Super Bright Yellow

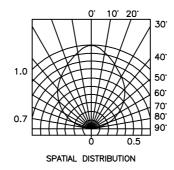
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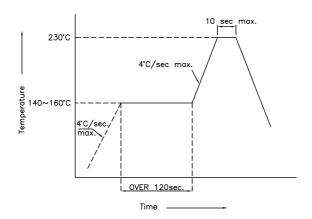


SPEC NO: DSAD1120 REV NO: V.2 DATE: FEB/28/2005 PAGE: 3 OF 4

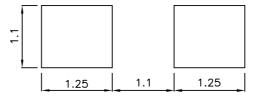
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SMT Reflow Soldering Instructions

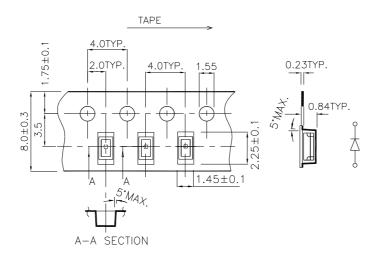
Number of reflow process shall be 2 times or less and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



SPEC NO: DSAD1120 REV NO: V.2 DATE: FEB/28/2005 PAGE: 4 OF 4